SK 85 MH 10 T



SEMITOP[®] 2

MOSFET Module

SK 85 MH 10 T

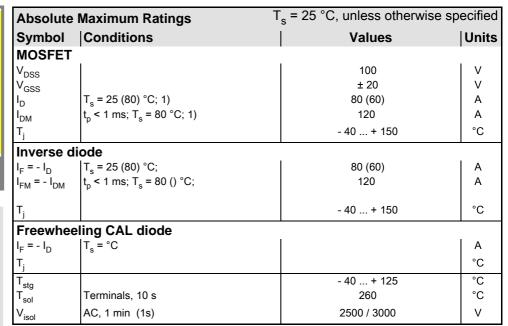
Preliminary Data

Features

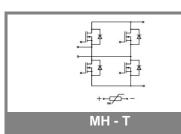
- Compact design
- One screw mounting
- Heat transfer and isolation through direct copper bonding aluminium oxide ceramic (DBC)
- Trench-gate technology
- Short internal connections and low inductance case

Typical Applications*

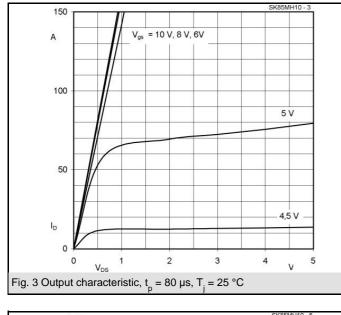
- Low switched mode power supplies
- DC servo drives
- UPS

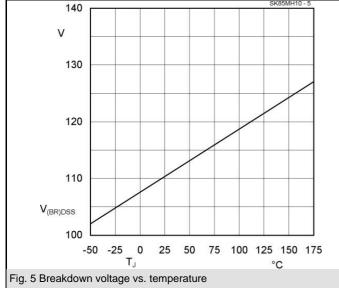


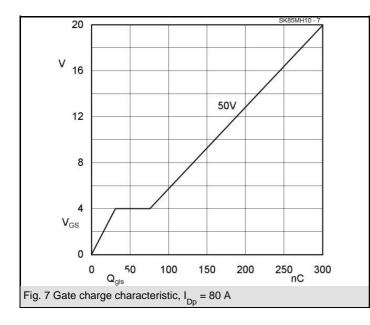
Characteristics		T _s = 25 °C,	T_s = 25 °C, unless otherwise specified			
Symbol	Conditions	min.	typ.	max.	Units	
MOSFE	г					
V _{(BR)DSS}	V _{GS} = 0 V, I _D = 5,6 mA	100			V	
V _{GS(th)}	$V_{GS} = V_{DS}; I_{D} = 5,6 \text{ mA}$	2,5	3,3		V	
IDSS	$V_{GS} = 0 V; V_{DS} = V_{DSS}; T_{j} = 25 °C$			100	μA	
I _{GSS}	$V_{GS} = \pm 20V$; $V_{DS} = 0V$			100	nA	
R _{DS(on)}	I _D = 80 A; V _{GS} = 10 V; T _j = 25 °C			7,5	mΩ	
R _{DS(on)}	I_{D} = 80 A; V_{GS} = 10 V; T_{j} = 125 °C			13,5	mΩ	
C _{CHC}	per MOSFET				pF	
C _{iss}	under following conditions:		9,1		nF	
C _{oss}	V _{GS} = 0 V; V _{DS} = 25 V; f = 1 MHz		1,8		nF	
C _{rss}			1,6		nF	
L _{DS}					nH	
t _{d(on)}	under following conditions:		300		ns	
t _r	$V_{DD} = 50 \text{ V}; V_{GS} = 10 \text{ V};$ $I_{D} = 50 \text{ A}$		140		ns	
t _{d(off)}	R _G = 56 Ω		1550		ns	
t _f			150		ns	
R _{th(j-s)}	per MOSFET (per module)			1,1	K/W	
Inverse	diode	·				
V _{SD}	$I_{F} = 50 \text{ A}; V_{GS} = 0 \text{ V}; T_{j} = ^{\circ}\text{C}$		0,9		V	
I _{RRM}	under following conditions:		24		Α	
Q _{rr}	I_F = 50 A; T_{vj} = 25 °C; R_G = 56 Ω		0,9		μC	
t _{rr}	V _R = 65 A; di/dt = 100 A/µs		70		ns	
Free-wh	eeling diode					
V _F	$I_F = A; V_{GS} = V$				V	
I _{RRM}	under following conditions:				A	
Q _{rr}	$I_F = A; T_{vi} = °C$				μC	
t _{rr}	$V_r = A; di/dt = A/\mu s$				ns	
	ical data	I				
M1	mounting torque			2	Nm	
w			20		g	
Case						

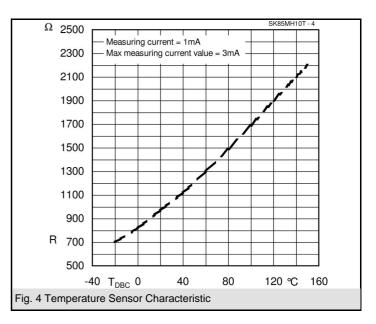


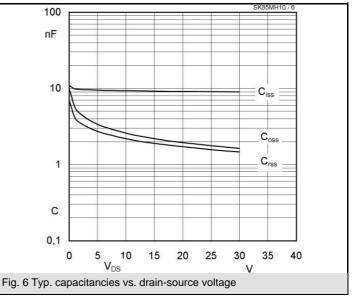
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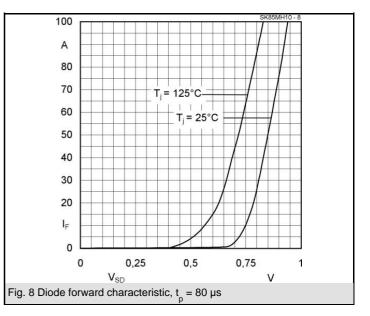




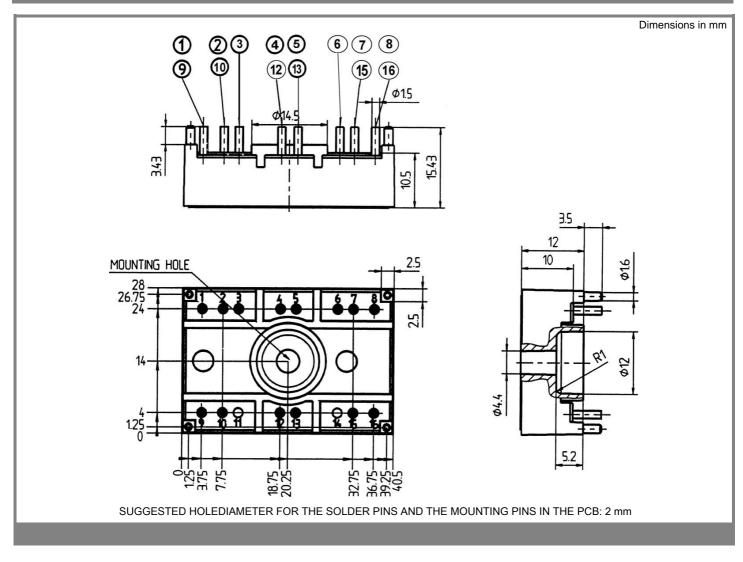


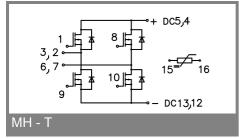






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This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, Chapter IX.

* The specifications of our components may not be considered as an assurance of component characteristics. Components have to be tested for the respective application. Adjustments may be necessary. The use of SEMIKRON products in life support appliances and systems is subject to prior specification and written approval by SEMIKRON. We therefore strongly recommend prior consultation of our personal.